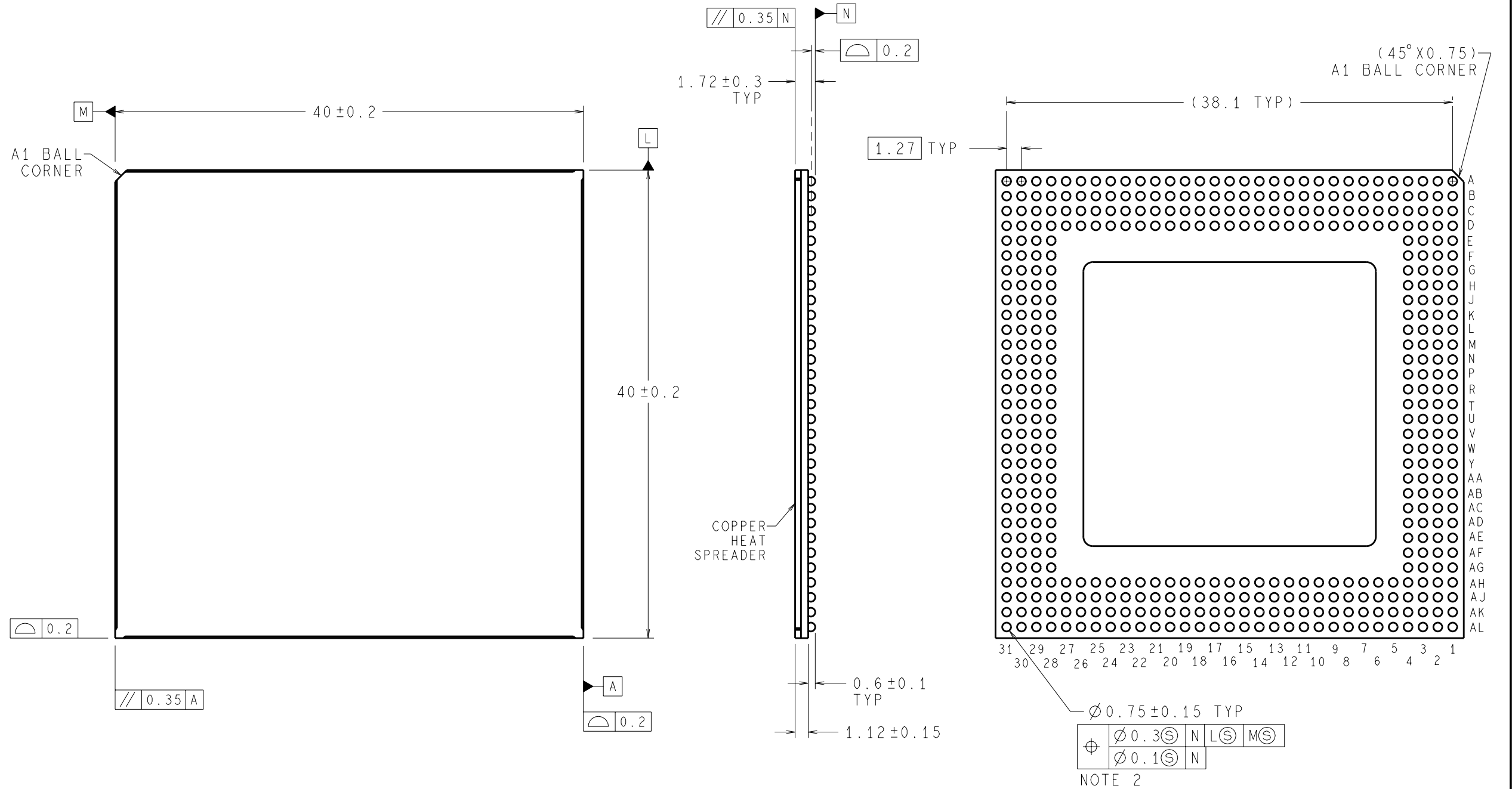


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	12357	02/10/2000	MS/AP
B	REVISE DWG & DWG TITLE PER ECN.	143	09/01/2000	MS/AP



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- SOLDER BALL COMPOSITION: Sn 63%, Pb 37%.
- DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM N.
- REFERENCE JEDEC REGISTRATION MO-151, VARIATION -1.00, DATED JUNE 1997.

APPROVALS		DATE	National Semiconductor		
DRAWN MARTA SUCHY		02/10/2000	2900 Semiconductor Dr., Santa Clara, CA 95052-8090		
DFTG. CHK. THANH LEQUANG		09/01/2000	EBGA, 40 X 40 X 1.72mm, 432 BALL, 1.27mm PITCH		
ENGR. CHK. ANINDYA PODDAR		09/01/2000			
		SCALE	SIZE	DRAWING NUMBER	REV
		N/A	C	(SC)MKT-UCL432A	B
		FORMERLY: N/A		SHEET 1 of 1	